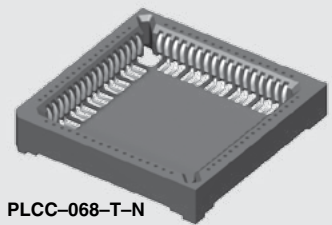


ICF-624-S-O



PLCC-068-T-N

(2.54 mm) .100" (ICF) (1.27 mm) .050" (PLCC)

ICF, PLCC SERIES

SMT DIP & CHIP CARRIER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?ICF or www.samtec.com?PLCC

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

BeCu

Plating:

Sn or Au over

50 μ " (1.27 μ m) Ni

Operating Temp Range:

-55 °C to +125 °C

Contact Resistance:

10 m Ω

Insertion Depth (ICF):

(2.54 mm) .100" to

(3.81 mm) .150"

Insertion

Force/Contact (ICF):

5 oz (1.39 N) average

Withdrawal

Force/Contact (ICF):

4 oz (1.11 N) average

RoHS Compliant:

Yes

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity (ICF):

.006" (0.15 mm) max

Lead Coplanarity (PLCC):

Less than 52 leads=

(0.15 mm) .006 max;

52 leads and more=

(0.20 mm) .008 max

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



FILE NO. E111594

Note:
Some sizes, styles and options are non-standard, non-returnable.

ICF

ROW SPACING & NO. OF CONTACTS

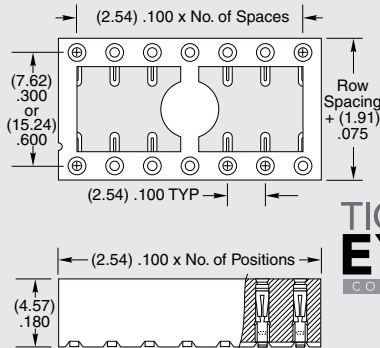
PLATING OPTION

TAIL OPTION

OTHER OPTION

Specify from chart below

"-XXX"	Row Space	No. of Contacts
-308	(7.62) .300	08
-314		14
-316		16
-318		18
-320		20
-324	(15.24) .600	24
-328		28
-624		24
-628		28
-632		32
-640		40



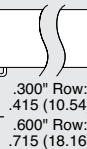
-S
=30 μ "
(0.76 μ m)
Gold on contact,
Matte Tin on tail

-T
= Matte Tin

-I
=Tails In



-O
=Tails Out



-TR
=Tape & Reel Packaging

PLCC

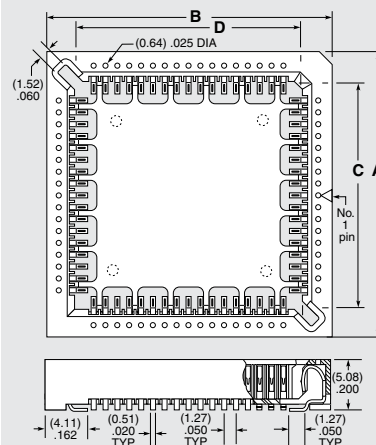
NO. OF CONTACTS

PLATING OPTION

ALIGNMENT PIN OPTION

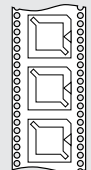
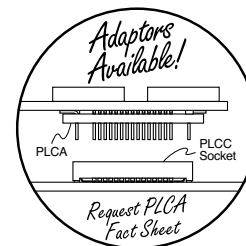
PACKAGE OPTION

-020, -032, -044, -068



*32 position has
(1.00 mm) .040 DIA x
(0.76 mm) .030 high
standoffs in corners.

NO. OF CONTACTS	A	B	C	D
-020	(15.24) .600	(15.24) .600	(9.40) .370	(9.40) .370
-032	(17.78) .700	(17.78) .700	(11.94) .470	(11.94) .470
-044	(22.86) .900	(22.86) .900	(17.02) .670	(17.02) .670
-068	(30.48) 1.200	(30.48) 1.200	(24.64) .970	(24.64) .970



Leave package option blank for packaging in a tube.